

ABSTRACT

The present invention provides:

a screen printing plate that is produced through an easy punching process at low costs in a short period, and that makes
5 it possible to easily carry out a printing process even on a base member such as a semiconductor wafer that is susceptible to scratches;

a screen printing plate characterized in that a sheet made of at least one kind of resin selected from the group
10 consisting of polyimide resins, polyetherimide resins and polyphenylenesulfide resins is subjected to a punching process by a numerically controlled punching machine, and is set on or over, or in a screen frame; and

a manufacturing method of a screen printing plate
15 characterized in that, after a sheet made from at least one kind of resin selected from the group consisting of polyimide resins, polyetherimide resins and polyphenylenesulfide resins is set on or over, or in a screen frame, the resin sheet is subjected to a punching process by a numerically controlled
20 punching machine, or after the sheet is clamped along its peripheral portion with a tension being applied thereto, the resin sheet is subjected to a punching process by a numerically controlled punching machine, and then set on or over, or in a screen frame.